

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. 09/449,025
Priority Filing Date November 24, 1999
Inventor Shozo Nagano et al.
Assignee..... Honeywell International, Inc.
Priority Group Art Unit 1775
Examiner Unknown
Attorney's Docket No. 30-5000-(4015)-Div1
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating
Anodes, Metal Alloys for Use as a Conductive Interconnection in an
Integrated Circuit; and Physical Vapor Deposition Targets

PRELIMINARY AMENDMENT

To: Box Patent Application
Assistant Commissioner for Patents
Washington, D.C. 20231

From: Mark S. Matkin (Tel. 509-624-4276; Fax 509-838-3424)
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Sir:

Please enter the following amendments prior to examining the above-identified application.

AMENDMENTS

In the Title

Please replace the title with the following: --CONDUCTIVE INTEGRATED CIRCUIT METAL ALLOY INTERCONNECTIONS, ELECTROPLATING ANODES; METAL ALLOYS FOR USE AS A CONDUCTIVE INTERCONNECTION IN AN INTEGRATED CIRCUIT; AND PHYSICAL VAPOR DEPOSITION TARGETS.--

In The Specification

At page 1 before the "Technical Field" section, please insert the following:

--RELATED PATENT DATA


This patent resulted from a divisional application of U.S. Patent Application Serial No. 09/449,025, filed November 24, 1999, entitled "Physical Vapor Deposition Targets, Conductive Integrated Circuit Metal Alloy Interconnects, Electroplating Anodes, and Metal Alloys For Use as a Conductive Interconnection in an Integrated Circuit", naming Shozo Nagano, Hinrich Hargarter, Jianxing Li and Jane Buehler as inventors, the disclosure of which is incorporated by reference.--

In the Claims

Cancel claims 1-30 and 34-59 without prejudice.

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Respectfully submitted,

By: 
Mark S. Matkin
Reg. No. 32,268

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